

# **Product Specification**

# PE43701

50 Ω RF Digital Attenuator 7-bit, 31.75 dB, 9 kHz - 4.0 GHz

#### **Features**

- HaRP™-enhanced UltraCMOS™ device
- Attenuation: 0.25 dB steps to 31.75 dB
- High Linearity: Typical 459 dBm IIP3
  - Excellent low-frequency performance
- 5.0 V Power Supply Voltage
- Fast switch settling time
- ogramming Modes:

  - d Parallel
  - Serial-Addressable Program up to oht addresses 000 - 111
- h-attenuation state @ power-up (PUP)
- CMOS Compatible
- No DC blo king capacitors required
- ackaged in a 32-lead 5x5x0.85 mm QFN

## **Product Description**

The PE43701 is a HaRP™-enhanced, high linearity, 7-bit RF Digital Step Attenuator (DSA). This highly versatile DSA covers a 31.75 dB attenuation range in 0.25 dB steps. The Peregrine  $50\Omega$  RF DSA provides a parallel or serialaddressable CMOS control interface. It maintains high attenuation accuracy over frequency and temperature and exhibits very low insertion loss and low power consumption. Performance does not change with V<sub>DD</sub> due to on-board regulator. This next generation Peregrine DSA is available in a 5x5 mm 32-lead QFN footprint.

The PE43701 is manufactured on Peregrine's UltraCMOS™ process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

Figure 1. Package Type

32-lead 5x5x0.85 mm QFN Package

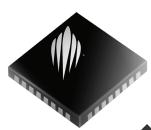


Figure 2. Functional Schematic Diagram

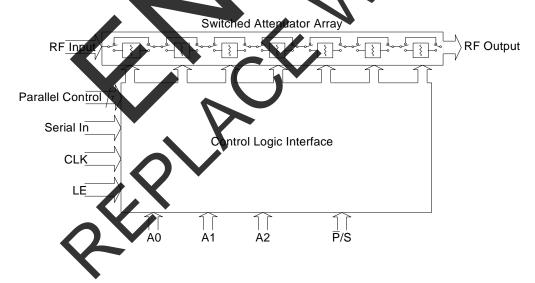




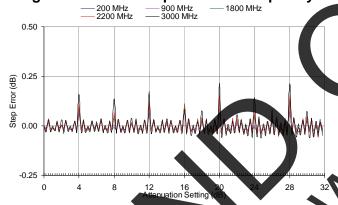
Table 1. Electrical Specifications @ +25°C, V<sub>DD</sub> = 3.3 V or 5.0 V

Parameter	Test Conditions	Frequency	Min	Typical	Max	Units
Frequency Range			9 kHz		4.0	GHz
Attenuation Range	0.25 dB Step			0 – 31.75		dB
Insertion Loss		9 kHz ≤4 GHz		1.9	2.4	dB
Attenuation Error	0 dB - 7.75 dB Attenuation settings 8 dB - 31.75 dB Attenuation settings 0 dB - 31.75 dB Attenuation settings	9 kHz < 3 GHz 9 kHz < 3 GHz 3 GHz ≤4 GHz			±(0.2+1.5%) ±(0.15+4%) ±(0.25+4.5%)	dB dB dB
Return Loss		9 kHz - 4 GHz		18		dB
Relative Phase	All States	9 kHz - 4 GHz		44		deg
P1dB (note 1)	Input	20 MHz - 4 GHz	30	32		dBm
IIP3	Two tones at +18 dBm, 20 MHz spacing	20 MHz - 4 GHz		59		dBm
Typical Spurious Value		1MHz		-110		dBm
Video Feed Through				10		mVpp
Switching Time	50% DC CTRL to 10% / 90% RF			650		ns
RF Trise/Tfall	10% / 90% RF		,	400		ns
Settling Time	RF settled to within 0.05 dB of final value RBW = 5 MHz, Averaging ON.			4	25	μs

Note 1. Please note Maximum Operating Pin ( $50\Omega$ ) of +23dBm as shown in Table 3.

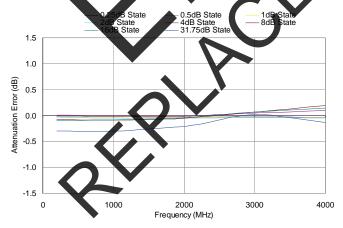
### **Performance Plots**

Figure 3. 0.25 dB Step Error vs. Frequency\*



<sup>\*</sup>Monotonicity is held so long as Step-Error does not cross below -0.

Figure 5. 0.25 dB Major State Bit Error



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Figure 4. 0.25dB Attenuation vs. Attenuation State

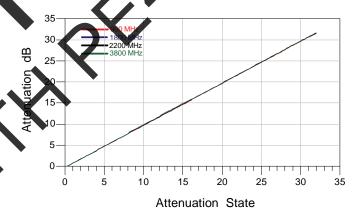


Figure 6. 0.25 dB Attenuation Error vs. Frequency

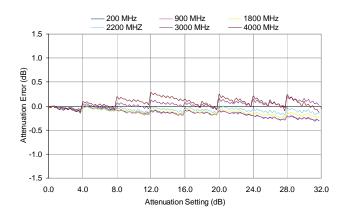




Figure 7. Insertion Loss vs. Temperature

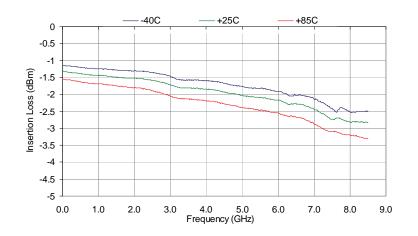


Figure 8. Input Return Loss vs. Attenuation:

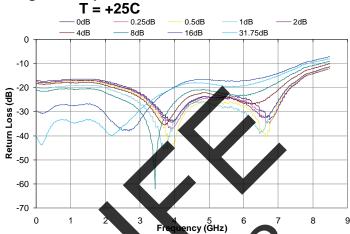


Figure 9. Output Return Loss vs. Attenuation:

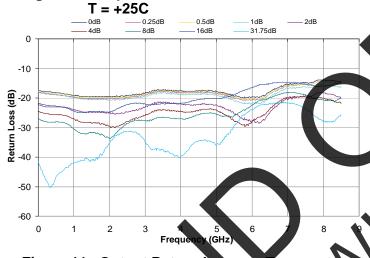


Figure 10. Input Return Loss vs. Temperature: 16dB State

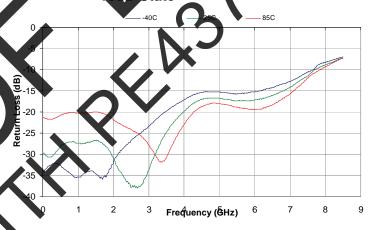


Figure 11. Output Return Loss vs. Temperature: 16dB State

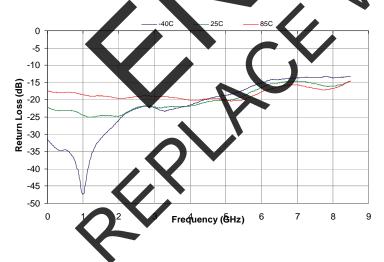
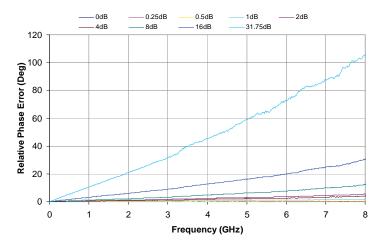


Figure 12. Relative Phase vs. Frequency



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Figure 13. Relative Phase vs. Temperature: 31.75dB State

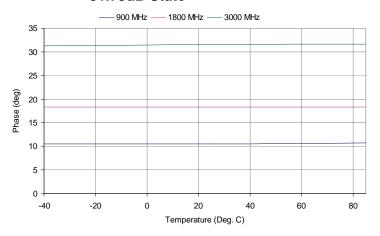


Figure 14. Attenuation Error vs. Attenuation

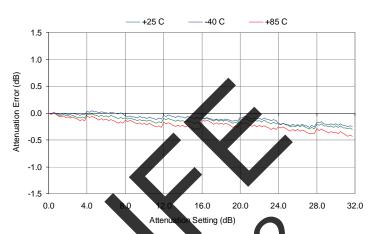


Figure 15. Attenuation Error vs. Attenuation Setting: 1800 MHz

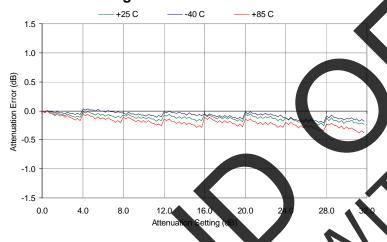


Figure 16. Attenuation Error vs. Attenuation Setting: 3000 MHz

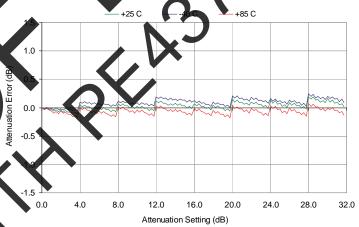
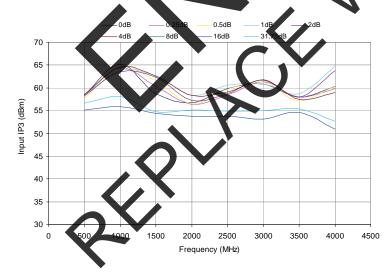


Figure 17. Input IP3 vs. Frequency



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Figure 18. Pin Configuration (Top View)

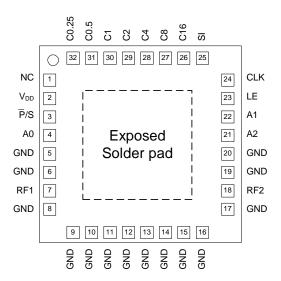


Table 2. Pin Descriptions

Pin No.	Pin Name	Description
1	N/C	No Connect
2	$V_{DD}$	Power supply pin
3	₽/S	Serial/Parallel mode select
4	A0	Address Bit A0 connection
5, 6, 8-17, 19, 20	GND	Ground
7	RF1	RF1 port
18	RF2	RF2 port
21	A2	Address Bit A2 connection
22	A1	Address Bit A1 connection
23	LE	Serial interface Latch Enable input
24	CLK	Serial interface Clock input
25	SI	Serial interface Data input
26	C16 (D6)	Parallel control bit, 16 dB
27	C8 (D5)	Parallel control bit, 8 dB
28	C4 (D4)	Parallel control bit, 4 dB
29	C2 (D3)	Parallel control bit, 2 dB
30	C1 (D2)	Rarallel control bit, 1 dB
31	C0.5 (D1)	Parallel control bit, 0.5 dB
32	C0.25 (D0)	Parallel control bit, 0.25 dB
Paddle	GND	Ground for proper operation

Note: Grand <u>C0.25</u>, C0.5, C1, C2, C4, C8, C16 if not in use.

# **Electrostatic Discharge (ESD) Precautions**

When handling this UltraCMOS™ device, observe the same precautions that you would use with other ESDsensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

## Latch-Up Avoidance

Unlike conventional CMOS dev UltraCMOS™ devices are immune to latch-up.

#### Moisture Sensitivity L

The Moisture Sensitivity Level rating for the PE43701 in the 5x5 QFN package is M

# Switching Frequency

The PE43701 has a maximum 5 kHz switching rate. Switching rate fined to be the speed at which the DSA can be toggled acros tenuation states.

## xposed Solder Pad Connection

he exposed solder pad on the bottom of the package d for proper device operation. be ground



**Table 3. Operating Ranges** 

Parameter	Min	Тур	Max	Units
V <sub>DD</sub> Power Supply Voltage	3.0	3.3		V
V <sub>DD</sub> Power Supply Voltage		5.0	5.5	V
I <sub>DD</sub> Power Supply Current		70	350	μΑ
Digital Input High	2.6		5.5	V
P <sub>IN</sub> Input power (50Ω): 9 kHz ≤20 MHz 20 MHz ≤4 GHz			See fig. 19 +23	dBm dBm
T <sub>OP</sub> Operating temperature range	-40	25	85	°C
Digital Input Low	0		1	٧
Digital Input Leakage <sup>1</sup>			15	μΑ

Note 1. Input leakage current per Control pin

**Table 4. Absolute Maximum Ratings** 

Symbol	Parameter/Conditions	Min	Max	Units
$V_{DD}$	Power supply voltage	-0.3	6.0	V
Vı	Voltage on any Digital input	-0.3	5.8	V
P <sub>IN</sub>	Input power (50Ω) 9 kHz ≤20 MHz 20 MHz ≤4 GHz		See fig. 19 +23	dBm dBm
T <sub>ST</sub>	Storage temperature range	-65	150	°C
V <sub>ESD</sub>	ESD voltage (HBM) ESD voltage (Machine Model)		500 100	V V

Note: 1. Human Body Model (HBM, MIL\_STD 883 Method 3015.7)

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Figure 19. Maximum Power Handling Capability: 70 = 50.0

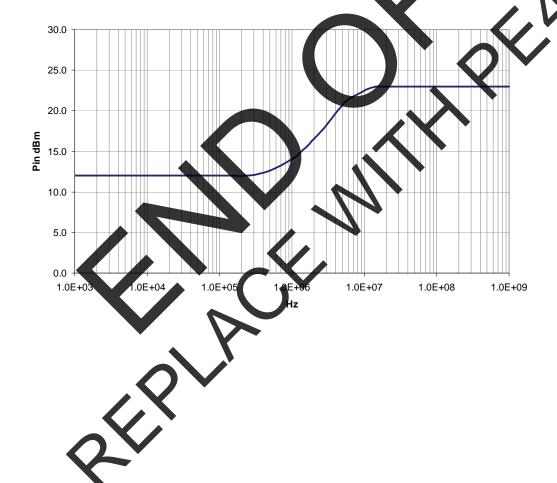




Table 5. Control Voltage

State	Bias Condition
Low	0 to +1.0 Vdc at 2 μA (typ)
High	+2.6 to +5 Vdc at 10 μA (typ)

### **Table 6. Latch and Clock Specifications**

Latch Enable Shift Clock		Function
0	1	Shift Register Clocked
1	×	Contents of shift register transferred to attenuator core

**Table 7. Parallel Truth Table** 

	F	Attenuation					
D6	D5	D4	D3	D2	D1	D0	Setting RF1-RF2
L	L	L	L	L	L	L	Reference I.L.
L	L	L	L	L	L	Н	0.25 dB
L	L	L	L	L	Н	L	0.5 dB
L	L	L	L	Н	L	L	1 dB
L	L	L	Н	L	L	L	2 dB
L	L	Н	L	L	L	L	4 dB
L	Н	L	L	L	L	L	8 dB
Н	L	L	L	L	L		16 dB
Н	Н	Н	Н	Н	Н	H	31.75 dB

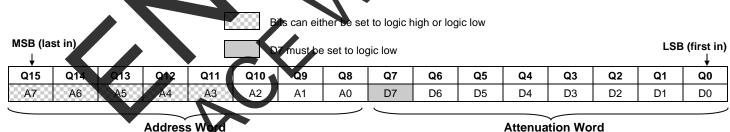
**Table 8. Address Word Truth Table** 

	Address Word									
A7 (MSB)	A6	A5	A4	А3	A2	<b>A</b> 1	A0	Address Setting		
Х	Х	Х	Х	Х	L	L	L	000		
Х	Х	Х	Х	Х	L	$\perp$	Н	001		
Х	Х	Х	Х	Х	L	Н	L	010		
Х	Х	Х	Х	Х	1	Н	Н	011		
Х	Х	Х	Х	X	1	L	L	100		
Х	Х	Х	Х	X	Н		H	101		
Х	Х	Х	X	Х	Н	Н		110		
Х	Х	X	X	X	Н	Н	Н	111		

Table 9. Attenuation Word Truth Table

	Attenuation							
D7	D6	<b>D</b> 5	D4	33	D2	<b>D</b> 1	D0 (LSB)	Setting RF1-RF2
٦	L	L		L			L	Reference I.L.
	L	L	L	Ť		L	Н	0.25 dB
7	L	L	L	F		П	L	0.5 dB
٦	L	L	L	V	Н	L	L	1 dB
	L	}	Y	*	L	L	L	2 dB
L	L	T	H	L	L	L	L	4 dB
L	L	Y	L	L	L	L	L	8 dB
L	X	L	L	L	L	L	L	16 dB
X	Н	Н	Н	Н	Н	Н	Н	31.75 dB

Table 10. Serial-Addressable Register Map



Attenuation Word derived directly from the attenuation value. For example, to program the 18.25 dB state at address 3

d: XXXXXX011

tion Word: Multiply by 4 and convert to binary  $\rightarrow$  4 \* 18.25 dB  $\rightarrow$  73  $\rightarrow$  01001001

ial Input: XXXXX01101001001



## **Programming Options**

#### Parallel/Serial-Addressable Selection

Either a parallel or serial-addressable interface can be used to control the PE43701. The P/S bit provides this selection, with  $\overline{P}/S=LOW$  selecting the parallel interface and P/S=HIGH selecting the serialaddressable interface.

#### Parallel Mode Interface

The parallel interface consists of seven CMOScompatible control lines that select the desired attenuation state, as shown in Table 7.

The parallel interface timing requirements are defined by Fig. 21 (Parallel Interface Timing Diagram), Table 12 (Parallel Interface AC Characteristics), and switching speed (*Table 1*).

For *latched*-parallel programming the Latch Enable (LE) should be held LOW while changing attenuation state control values, then pulse LE HIGH to LOW (per Fig. 21) to latch new attenuation state into device.

For *direct* parallel programming, the Latch Enable (LE) line should be pulled HIGH. Changing attenuation state control values will change device state to new attenuation. Direct Mode is ideal to manual control of the device (using hardwire, switches, or jumpers).

#### Serial-Addressable Interfact

The serial-addressable interface is a 16-bit serial-in, parallel-out shift register buffered by a transparent latch. The 16-bits make up two words comprised of 8-bits each. The first word is the Attenuation Word which controls the state of the DSA. The second word is the Address Word, which is compared to the static (or o ogrammed) logical states of the A0 A1 and A2 digital inputs. If there is an address match, the DSA changes state, otherwise its current state will remain unchanged. Fig. 20 illustrates an example timing diagram for programming a state. It is required that all parallel control inputs be grounded when the DSA is used in serialaddressable Mode

The serial-addressable interface is controlled using three CMOS-compatible signals: Serial-In (SI), Clock (CLK) and Latch Enable (LE). The SI and CLK inputs allow data to be serially entered into the shift register. Serial data is clocked in LSB first, beginning with the Attenuation Word.

The shift register must be loaded while LE is held LOW to prevent the attenuator value from changing as data is entered. The LE input should then be toggled HIGH and brought LOW again, latching the new data into the DSA. Address word and attenuation word truth tables are listed in Table 8 & Table 9, respectively. A programming example of the serial-addressable register is illustrated in Table 10. The serial-addressable timing diagram is illustrated in Fig. 20.

# **Power-up Control Settings**

The PE43701 will always initialize to the maximum attenuation setting (31.75 dB) on power-up for both the serial addressable and latched-parallel modes of operation and will remain in this setting until the user latches in the next programming word. In directparallel mode, the DSA can be preset to any state ithin the 31.75 dB range by pre-setting the parallel control pins prior to power up. In this mode, there is 400-us delay between the time the DSA is powered-up to the time the desired state is set. During this power-up delay, the device attenuates to the maximum attenuation setting (31.75 dB) before defaulting to the user defined If the control pins are left floating in this mode during power-up, the device will default to the minimum attenuation setting (insertion loss state).

Dynamic operation between serial-addressable and parallel programming modes is possible.

If the DSA powers up in serial-addressable mode (P/ S = HIGH), all the parallel control inputs DI[6:0] must be set to logic low. Prior to toggling to parallel mode, the DSA *must* be programmed serially to ensure D[7] is set to logic low.

If the DSA powers up in either latched or directparallel mode, all parallel pins DI[6:0] must be set to logic low prior to toggling to serial-addressable mode  $(\overline{P}/S = HIGH)$ , and *held* low until the DSA has been programmed serially to ensure bit D[7] is set to logic low.

The sequencing is only required once on powerup. Once completed, the DSA may be toggled between serial-addressable and parallel programming modes at will.

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Figure 20. Serial-Addressable Timing Diagram

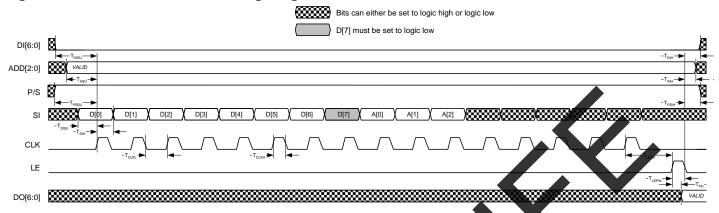


Figure 21. Latched-Parallel/Direct-Parallel Timing Diagram

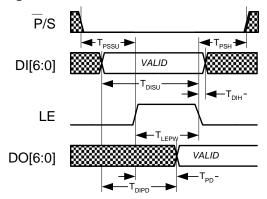


Table 11. Serial-Addressable Interface **AC Characteristics** 

 $V_{DD} = 3.3$  or 5.0 V, -40° C <  $T_A$  < 85° C, unless otherwise specified

Symbol	Parameter	Min	Max	Unit '
F <sub>CLK</sub>	Serial clock frequency	V	10	MHz
T <sub>CLKH</sub>	Serial clock HIGH time	30	- '	ns
T <sub>CLKL</sub>	Serial clock LOW time	30	_	ns
$T_{LESU}$	Last serial clock rising edge setup time to Latch Enable rising edge	10		ns
T <sub>LEPW</sub>	Latch Enable min. pulse width	30		ns
T <sub>SISU</sub>	Serial data setup time	10	) -	ns
T <sub>SIH</sub>	Serial data hold time	10	-	ns
T <sub>DISU</sub>	Parallel data setup time	90	-	ns
T <sub>DIH</sub>	Parallel data hold time	100	-	ns
T <sub>ASU</sub>	Address setup time	100	-	ns
T <sub>AH</sub>	Address hold time	100	-	ns
T <sub>PSSU</sub>	Parallel/Serial setup time	100	-	ns
T <sub>PSH</sub>	Parallel Serial hold time	100	-	ns
$T_PD$	Digital register delay (internal)	-	10	ns

Table 12. Parallel and Direct Interface **AC Characteristics** 

 $V_{\rm DD}$  = 8.3 or 5.0 V, -40° C < T<sub>A</sub> < 85° C, unless otherwise specified

Symbol	Parameter	Min	Max	Unit
T <sub>LEPW</sub>	Latch Enable minimum pulse width	30	-	ns
T <sub>DISU</sub>	Parallel data setup time	100	-	ns
T <sub>DIH</sub>	Parallel data hold time	100	-	ns
T <sub>PSSU</sub>	Parallel/Serial setup time	100	-	ns
T <sub>PSIH</sub>	Parallel/Serial hold time	100	-	ns
T <sub>PD</sub>	Digital register delay (internal)	-	10	ns
T <sub>DIPD</sub>	Digital register delay (internal, direct mode only)	-	5	ns



#### **Evaluation Kit**

The Digital Attenuator Evaluation Kit board was designed to ease customer evaluation of the PE43701 Digital Step Attenuator.

Direct-Parallel Programming Procedure For automated direct-parallel programming, connect the test harness provided with the EVK from the parallel port of the PC to the J1 & Serial header pin and set the D0-D6 SP3T switches to the 'MIDDLE' toggle position. Position the Parallel/ Serial  $(\overline{P}/S)$  select switch to the Parallel (or left) position. The evaluation software is written to operate the DSA in either Parallel or Serial-Addressable Mode. Ensure that the software is set to program in Direct-Parallel mode. Using the software, enable or disable each setting to the desired attenuation state. The software automatically programs the DSA each time an attenuation state is enabled or disabled.

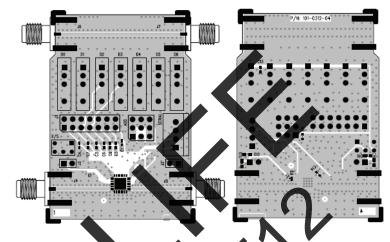
For manual direct-parallel programming, disconnect the test harness provided with the from the J1 and Serial header pins. Position the Parallel/Serial (P/S) select switch to the Parallel (or left) position. The LE pin on the Serial header must be tied to V<sub>DD</sub>. Switches D0-D6 are SP3T switches which enable the user to manually program the parallel bits. When any input D0-D6 is toggled 'UP', logic high is presented to the parallel input. When toggled 'DOWN', logic low is presented to the parallel input. Setting 00-D6 to the 'MDDLE' toggle position presents an OREN, which forces on-chip logic low. Table 9 depicts the parallel programming truth table and Fig. 21 illustrates the parallel programming timing diagram.

Latched-Parallel Programming Procedure For automated (atched-parallel programming, the procedure is identical to the direct-parallel method. The user only must ensure that Latched-Parallel is selected in the software

For manual latched-parallel programming, the procedure is identical to direct-parallel except now the LE pin or the Serial header must be logic low as the parallel its are applied. The user must then pulse LE from 0V to V<sub>DD</sub> and back to 0V to latch the programming word into the DSA. LE must be logic low prior to programming the next word.

#### Figure 22. Evaluation Board Layout

Peregrine Specification 101-0312



Note: Reference Fig. 23 for Evaluation on Board Schematic

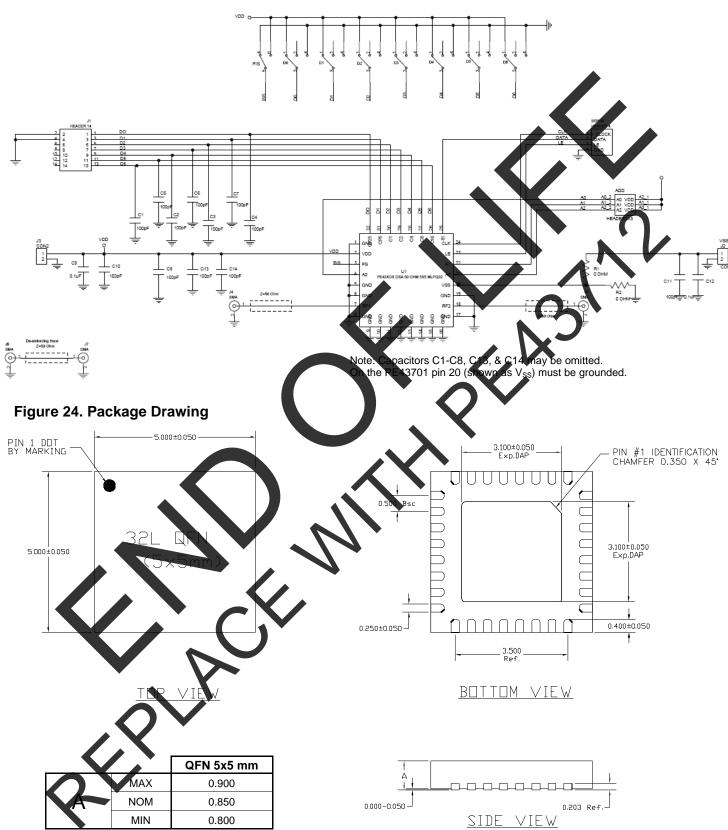
Serial-Addressable Programming Procedure
Position the Parallel/Serial (P/S) select switch to he Serial (or right) position. Prior to programming, the user must define an address setting using the ADD header pin. Jump the middle plas on the ADD header A0-A2 (or lower) row of pins to set logic high, or jump the middle pins to the upper row of pins to set logic low. If the ADD pins are left open, then 000 become the default address. The evaluation software is written to operate the DSA in either Parallel or Sérial-Addressable Mode. Ensure that the software is set to program in Serial-Addressable mode. Using the software, enable or disable each setting to the desired attenuation state. The software automatically programs the DSA each time an attenuation state is enabled or disabled.



Figure 23. Evaluation Board Schematic

Peregrine Specification 102-0381

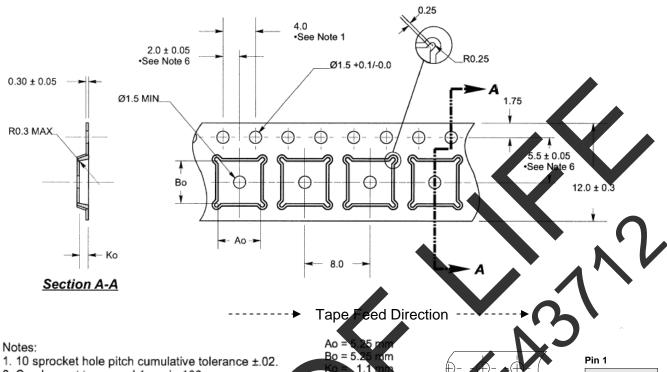
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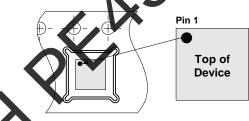
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Figure 25. Tape and Reel Drawing



- 2. Camber not to exceed 1mm in 100mm.
- 3. Material: PS + C.
- 4. Ao and Bo measured as indicated.
- Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole



Device Orientation in Tape

Figure 26. Marking Specifications



Table 13. Ordering Information

Order Code Part Marking		Description	Package	Shipping Method	
PE43701ML	43701	PE43701 G - 32QFN 5x5mm-75A	Green 32-lead 5x5mm QFN	Bulk or tape cut from reel	
PE43701 MLI-Z	43701	PE43701 G – 32QFN 5x5mm-3000C	Green 32-lead 5x5mm QFN	3000 units / T&R	
EK43701-01	43701	PE43701 G - 32QFN 5x5mm-EK	Evaluation Kit	1 / Box	

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